

ABSTRACT

PACKAGED WAFER PROCESSING METHOD

A packaged wafer processing method is provided. The packaged wafer processing method includes a processing step of processing each division line formed on a packaged wafer by using a laser beam applying unit and a feeding mechanism and indexing the packaged wafer by a preset index amount a corresponding to the pitch of the division lines by using an indexing mechanism, thereby forming a laser processed groove along each division line, and a correcting step of imaging the next division line to be processed in an exposed peripheral portion of the packaged wafer and the laser processed groove just formed along the present division line, at any arbitrary time during the processing step, next determining the distance b between the next division line and the laser processed groove just formed along the present division line, and then calculating a correction index amount c by using the deviation corresponding to the difference $(a - b)$ between the preset index amount a and the distance b .

(Figure 4)